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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/814,059	03/30/2004	Byung-Sung Kwak	03-1498/LSI1P238	5738
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LSI LOGIC CORPORATION			EXAMINER	
1621 BARBER LANE			VAN, LUAN V	
MS: D-106			ART UNIT	PAPER NUMBER
MILPITAS, CA 95035			1753	

DATE MAILED: 08/09/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary	Application No.	Applicant(s)
	10/814,059	KWAK ET AL.
	Examiner Luan V. Van	Art Unit 1753

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) Responsive to communication(s) filed on 06 June 2006.
- 2a) This action is FINAL. 2b) This action is non-final.
- 3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) Claim(s) 3,4,6-16,21-23 and 25-28 is/are pending in the application.
- 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
- 5) Claim(s) _____ is/are allowed.
- 6) Claim(s) 3,4,6-16,21-23 and 25-28 is/are rejected.
- 7) Claim(s) _____ is/are objected to.
- 8) Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) The specification is objected to by the Examiner.
- 10) The drawing(s) filed on _____ is/are: a) accepted or b) objected to by the Examiner.
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
 - a) All b) Some * c) None of:
 1. Certified copies of the priority documents have been received.
 2. Certified copies of the priority documents have been received in Application No. _____.
 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- | | |
|---|---|
| 1) <input checked="" type="checkbox"/> Notice of References Cited (PTO-892) | 4) <input type="checkbox"/> Interview Summary (PTO-413) |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948) | Paper No(s)/Mail Date. _____ |
| 3) <input type="checkbox"/> Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)
Paper No(s)/Mail Date _____. | 5) <input type="checkbox"/> Notice of Informal Patent Application (PTO-152) |
| | 6) <input type="checkbox"/> Other: _____. |

DETAILED ACTION

Continued Examination Under 37 CFR 1.114

A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on June 6, 2006 has been entered.

Response to Amendment

Applicant's amendment of June 6, 2006 does not render the application allowable.

The amendment is objected to under 35 U.S.C. 132(a) because it introduces new matter into the disclosure. 35 U.S.C. 132(a) states that no amendment shall introduce new matter into the disclosure of the invention. The added material which is not supported by the original disclosure is as follows: Claim 28 recites the limitation of "said equilibration taking into consideration the diffusion coefficients for the additives." However, there is no evidence in the applicant's disclosure to support the recitation. The disclosure, therefore, does not provide a clear indication to support the limitation . Applicant is required to cancel the new matter in the reply to this Office Action.

Status of Objections and Rejections

The rejection of claims 1, 2, 5, 17-20 and 24 is obviated by Applicant's cancellation.

All rejections from the previous office action are withdrawn in view of Applicant's amendment.

New grounds of rejection under 35 U.S.C. 103(a) are necessitated by the amendments.

Claim Rejections - 35 USC § 112

The following is a quotation of the first paragraph of 35 U.S.C. 112:

The specification shall contain a written description of the invention, and of the manner and process of making and using it, in such full, clear, concise, and exact terms as to enable any person skilled in the art to which it pertains, or with which it is most nearly connected, to make and use the same and shall set forth the best mode contemplated by the inventor of carrying out his invention.

Claim 28 is rejected under 35 U.S.C. 112, first paragraph, as failing to comply with the written description requirement. The claim(s) contains subject matter which was not described in the specification in such a way as to reasonably convey to one skilled in the relevant art that the inventor(s), at the time the application was filed, had possession of the claimed invention.

The claim recites the limitation of "said equilibration taking into consideration the diffusion coefficients for the additives." However, there is no evidence in the applicant's disclosure to support the recitation. The disclosure, therefore, does not provide a clear indication to support the limitation.

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

Claims 27 and 28 are rejected under 35 U.S.C. 102(e) as being anticipated by Mayer et al.

Regarding claim 27, Mayer et al. teach a method of planarizing a metal layer on a semiconductor substrate, the method comprising: providing a semiconductor substrate having a trench or via formed in a dielectric layer of the semiconductor substrate (column 2 line 54-63); forming the metal layer (column 3 lines 5-11) on the dielectric layer such that the metal layer at least fills the trenches or vias; immersing the substrate in an electrolyte plating solution having organic additives, the organic additives comprising at least one of plating accelerators, plating suppressors, and plating levelers (column 8 lines 32-61), and executing a series of cycles for removing the excess portions of the metal layer wherein said cycles include performing sequentially electropolishing followed by electroplating and equilibrating the electrolyte plating solution (column 20 lines 35-45). The equilibration is performed in a manner enabling the organic additive concentration to achieve local equilibrium before a next cycle begins (column 20 lines 41-45).

Regarding claim 28, Mayer et al. teach different induction period will occur for different additive species depending on their diffusivity in the plating bath and under the particular conditions of current and voltage (column 9 lines 46-49).

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

The factual inquiries set forth in *Graham v. John Deere Co.*, 383 U.S. 1, 148 USPQ 459 (1966), that are applied for establishing a background for determining obviousness under 35 U.S.C. 103(a) are summarized as follows:

1. Determining the scope and contents of the prior art.
2. Ascertaining the differences between the prior art and the claims at issue.
3. Resolving the level of ordinary skill in the pertinent art.
4. Considering objective evidence present in the application indicating obviousness or nonobviousness.

Claims 3-4, 6-9, 16, 21-23 and 25-28 are rejected under 35 U.S.C. 103(a) as being unpatentable over Bonkabeta et al. in view of Mayer et al.

Regarding claims 7 and 27-28, Bonkabeta et al. teach a method of planarizing a metal layer on a semiconductor substrate, the method comprising: forming a trench or via (paragraph 31) in a dielectric layer of the semiconductor substrate; forming the metal layer (paragraph 34) on the dielectric layer such that the metal layer at least fills the trenches or vias; immersing the substrate (paragraph 32) in an electrolyte plating

solution having organic additives (paragraph 34), the organic additives comprising at least one of plating accelerators, plating suppressors, and plating levelers (such as the polymer phenazonium derivatives), and removing the excess portions of the metal layer by performing sequentially electropolishing followed by electroplating (figure 6a), wherein the polishing, plating, and relaxation operations comprise one cycle of a pass and wherein the method comprises at least two passes performed sequentially (see figure 6 a).

Bonkabeta et al. differ from the instant claims in that the reference does not explicitly discuss the relaxation period, although Bonkabeta et al. shows a time period (shown as a gap in figure 6a) of having no current in between the plurality of electrodepositing an electropolishing pulses.

However, even assuming that Bonkabeta et al. does not teach the relaxation period, using a relaxation time period is conventionally known in the art. For example, Mayer et al. teach a method in which multiple cathodic pulses (i.e., electroplating) with off times (i.e., relaxation operations) and multiple anodic pulses (i.e., electropolishing) with off times (column 20 lines 35-39). Further, Mayer et al. explains that no current is supplied during an off time period during which relaxation and replenishment of additive and copper ions in the via occurs (column 20 lines 41-45).

It would have been obvious to one having ordinary skill in the art at the time the invention was made to have modified the method of Bonkabeta et al. by using relaxation period of Mayer et al., because it would allow the replenishment of additive and copper ions in the via, thus enabling the additives to equilibrate.

Regarding claims 8-9, Bonkabeta et al. differ from the instant claims in that the reference does not explicitly disclose the specific ratio of electropolishing rate to electroplating rate of the instant claim nor decreasing the ratio of electropolishing rate to electroplating rate to about 1.0.

However, Bonkabeta et al. teach that in electropolishing the integral of the amperage of an electropolishing/electroplating sequence (i.e., pass) must be less than zero (paragraph 55), since the integral of the electropolishing amperage is greater than the integral of the electroplating amperage. Therefore, the ratio of the integral of the electropolishing amperage to that of the electroplating amperage must be greater than 1.0. In order for electropolishing or net removal of metal to occur, the electropolishing rate to electroplating rate ratio must be greater than 1.0. Since Bonkabeta et al. teach that the performance of their method may be influenced by process parameters such as "temperature of the electrolyte, the time dependence of applied currents, in particular amperages and durations of pulses, numbers of applied pulses and angular frequencies, the geometrical arrangement of components of the plating cell, concentrations of components of the electrolyte, in particular concentrations of conductor metal ions and additives, and the conductivity of the electrolyte" (paragraph 62), it would have been obvious to one having ordinary skill to have optimized through routine experimentation the ratio of the electropolishing rate to electroplating rate to that of the instant claim in order to reduce the total process time to deposit the metal layer, the likelihood of the formation of trapped voids filled with electrolyte in narrow vias and the roughness of the metal layer which is obtained after the electropolishing process

(paragraph 63). It would have been obvious to one having ordinary skill in the art at the time the invention was made to have further modified the method of Bonkabeta et al. by reducing the ratio of the electropolishing rate to electroplating rate to about 1.0 when the process is about complete in order to prevent over polishing of the metal layer. Furthermore, it would not be desirable to reduce the ratio to less than 1 unless net deposition of metal is desired.

Regarding claim 3, Bonkabeta et al. teach the concentrations of the organic additives are selected such that the plating rate is greater than the electropolishing rate in a topography dependant fashion, since the plating method and composition (paragraph 34) of Bonkabeta et al. is same as that of the instant claims.

Regarding claim 4, Bonkabeta et al. teach the topography dependant fashion comprises increasing the rate of plating at corners of trenches or vias, since the plating method and composition (paragraph 34) of Bonkabeta et al. is same as that of the instant claims.

Regarding claim 6, Bonkabeta et al. teach the removal rate of electropolishing is controlled by one of adjusting the voltage applied (or amperage, paragraph 44) to the electrodes in the electrolytic solution and the duration (paragraph 45) of the applied voltage.

Regarding claim 16, Bonkabeta et al. teach using the wafer wide polisher 103 (figure 1).

Regarding claim 21-23, Bonkabeta et al. teach a method of planarizing a metal layer on a semiconductor substrate, the method comprising: providing a semiconductor

substrate having a trench or via (paragraph 31) in a dielectric layer of the substrate; filling the trenches and vias with a metal layer (paragraph 34); spraying the substrate (paragraph 69) in an electrolyte plating solution having organic additives (paragraph 34), the organic additives comprising at least one of plating accelerators, plating suppressors, and plating levelers (such as the polymer phenazonium derivatives), and planarizing the metal layer by implementing a series of pulses comprising sequential electropolishing 601 followed by electroplating 605 (figure 6a). Bonkabeta et al. further teach that in electropolishing the integral of the amperage of an electropolishing/electroplating sequence (i.e., pass) must be less than zero (paragraph 55), since the integral of the electropolishing amperage is greater than the integral of the electroplating amperage. Therefore, the ratio of the integral of the electropolishing amperage to that of the electroplating amperage must be greater than 1.0. In order for electropolishing or net removal of metal to occur, the electropolishing rate to electroplating rate ratio must be greater than 1.0.

Bonkabeta et al. differ from the instant claims in that the reference does not explicitly disclose the specific ratio of electropolishing rate to electroplating rate of the instant claim nor decreasing the ratio of electropolishing rate to electroplating rate to about 1.0. Bonkabeta et al. also differ from the instant claims in that the reference does not explicitly discuss the relaxation period, although Bonkabeta et al. shows a time period (shown as a gap in figure 6a) of having no current in between the plurality of electrodepositing an electropolishing pulses.

However, even assuming that Bonkabeta et al. does not teach the relaxation period, using a relaxation time period is conventionally known in the art. For example, Mayer et al. teach a method in which multiple cathodic pulses (i.e., electroplating) with off times (i.e., relaxation operations) and multiple anodic pulses (i.e., electropolishing) with off times (column 20 lines 35-39). Further, Mayer et al. explains that no current is supplied during an off time period during which relaxation and replenishment of additive and copper ions in the via occurs (column 20 lines 41-45).

It would have been obvious to one having ordinary skill in the art at the time the invention was made to have modified the method of Bonkabeta et al. by using relaxation period of Mayer et al., because it would allow the replenishment of additive and copper ions in the via, thus enabling the additives to equilibrate.

Since Bonkabeta et al. teach that the performance of their method may be influenced by process parameters such as "temperature of the electrolyte, the time dependence of applied currents, in particular amperages and durations of pulses, numbers of applied pulses and angular frequencies, the geometrical arrangement of components of the plating cell, concentrations of components of the electrolyte, in particular concentrations of conductor metal ions and additives, and the conductivity of the electrolyte" (paragraph 62), it would have been obvious to one having ordinary skill to have optimized through routine experimentation the ratio of the electropolishing rate to electroplating rate to that of the instant claim in order to reduce the total process time to deposit the metal layer, the likelihood of the formation of trapped voids filled with electrolyte in narrow vias and the roughness of the metal layer which is obtained after

the electropolishing process (paragraph 63). It would have been obvious to one having ordinary skill in the art at the time the invention was made to have further modified the method of Bonkabeta et al. by reducing the ratio of the electropolishing rate to electroplating rate to about 1.0 when the process is about complete in order to prevent over polishing of the metal layer. Furthermore, it would not be desirable to reduce the ratio to less than 1 unless net deposition of metal is desired. With respect to the variations in the localized polishing rates and plating rates (claim 21), the method of Bonkabeta et al. would inherently perform the same processes, since Bonkabeta et al. use the same additives and sequential planarizing process have a electropolishing rate to electroplating rate ratio of greater than 1.0 as those of the instant claim as addressed above.

Regarding claims 25-26, Bonkabeta et al. teach the organic additives include bis-3-sulfopropyl disulfide (paragraph 34).

Claims 10-14 are rejected under 35 U.S.C. 103(a) as being unpatentable over Bonkabeta et al. in view of Mayer et al., and further in view of Reid et al.

Bonkabeta et al. teach the method as described above. The difference between the reference to Bonkabeta et al. and the instant claims is that the reference does not explicitly teach the specific concentrations of the additives of the instant claims, although Bonkabeta et al. disclose that the performance (i.e., the likelihood of void formation in the vias and the roughness of the metal layer, paragraph 63) can be influenced by process parameters such as "concentrations of components of the

electrolyte, in particular concentration of conductor metal ions and additives" (paragraph 62) etc.

Reid et al. teach an electroplating method wherein the solution comprises: a leveler at a concentration of between about 0.5-8 ml/L (Table 1); a suppressor at a concentration of between about 1-6 ml/L; and an accelerator at a concentration of between about 0.5-8 ml/L. The ranges of concentration as taught by Reid et al. are within the ranges of the instant claims.

It would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the electroplating method of Bonkabeta et al. and Mayer et al. by using additive concentrations of Reid et al., because such concentrations are suitable for electroplating to produce metal films and features without voids or defects (paragraph 7).

Claims 15 are rejected under 35 U.S.C. 103(a) as being unpatentable over Bonkabeta et al. in view of Mayer et al., and further in view of Datta et al.

Bonkabeta et al. teach the method as described above. The difference between the reference to Bonkabeta et al. and the instant claims is that the reference teach a spray of electrolyte (paragraph 69) but does not explicitly teach moving the spray from the center to the edge of the wafer (claim 15).

Datta et al. teach an electropolishing process using a linear electrode with a nozzle assembly which is scanned slowly back-and-forth over the anode, parallel to the substrate surface (column 8 lines 43-45).

It would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the electroplating method of Bonkabeta et al. and Mayer et al. by moving the spray across the substrate as taught by Datta et al., because it would enable metal to be removed at a high rate of speed (column 10 lines 22-24).

Response to Arguments

Applicant's arguments have been fully considered but they are not persuasive.

In the arguments presented on page 9 of the amendment, the applicant argues that Bonkabeta et al. do not teach the relaxation operation of the instant claim. Without acquiescing to the applicant's argument, the examiner acknowledges that Bonkabeta et al. differ from the instant claims in that the reference does not explicitly discuss the relaxation period, although Bonkabeta et al. shows a time period (shown as gaps in figure 6a) of having no current in between the plurality of electrodepositing an electropolishing pulses. However, even assuming that Bonkabeta et al. does not teach the relaxation period, using a relaxation time period is conventionally known in the art. For example, Mayer et al. teach a method in which multiple cathodic pulses (i.e., electroplating) with off times (i.e., relaxation operations) and multiple anodic pulses (i.e., electropolishing) with off times (column 20 lines 35-39). Further, Mayer et al. explain that no current is supplied during an off time period during which relaxation and replenishment of additive and copper ions in the via occurs (column 20 lines 41-45). It would have been obvious to one having ordinary skill in the art at the time the invention was made to have modified the method of Bonkabeta et al. by using relaxation period of

Mayer et al., because it would allow the replenishment of additive and copper ions in the via, thus enabling the additives to equilibrate.

Conclusion

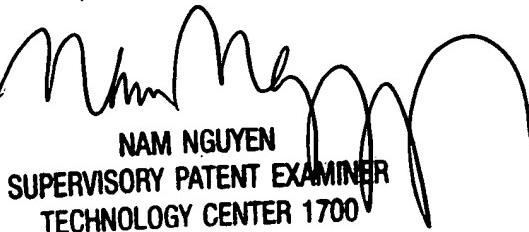
Any inquiry concerning this communication or earlier communications from the examiner should be directed to Luan V. Van whose telephone number is 571-272-8521. The examiner can normally be reached on M-F 9:30-6:00.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nam Nguyen can be reached on 571-272-1342. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

LVV

August 2, 2006



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